

## To investigate and model the key trade-offs, relevant to die attach adhesives for packaging/ CoB assembly of stress sensitive devices linked to the WP2 round-robin modelling activity

### Objective

The overall programme will look at 3 stress sensitive structures

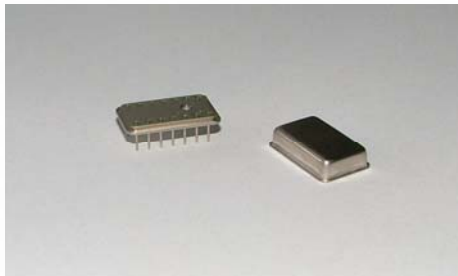
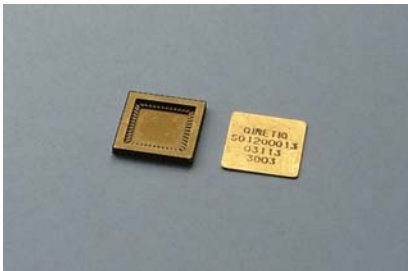
- Two Tyndall test structure arrays Fixed-fixed beams and cantilevers
- QinetiQ microphone

A number of different die attach adhesives will be used for the experimental work, with an appropriate range of CTE Modulus (stiffness) and thickness.

The round robin modelling will concentrate on a Kyocera 48 pin CLCC.

Additionally QinetiQ will consider a 14 pin DIL metal package and possibly PCB mounting of their microphone.

QinetiQ and Tyndall will perform comprehensive physical testing and modelling of their devices.



### Partners involved

QinetiQ, Tyndall Institute, Fraunhofer IZM Berlin, Centre Spatial de Liege, University of Lancaster and partners in the linked WP2 round-robin modelling activity

### Summary of results

New cross workpackages WP2 & WP4 project, started November 2005

### Offer to industry

Benchmarked and validated models for MEMS packaging, including poorly matched assemblies

### Contact

Alan Brown ([agbrown@QinetiQ.com](mailto:agbrown@QinetiQ.com)), Orla Slattery ([orla.slattery@tyndall.ie](mailto:orla.slattery@tyndall.ie))

### Project status, date

New project started November 2005